

**AMENDMENTS TO THE CLAIMS**

The below listing of claims replaces all prior versions of claims in the application.

1. (Currently Amended) A semiconductor laser element comprising:

a plurality of ridges arranged in parallel with each other inside a pair of first supports protecting said ridges;

a pair of second supports provided between said plurality of ridges and protecting said ridges wherein electrodes are formed on each ridges;

a monitor region provided to an outermost edge of said semiconductor laser element to monitor progress of etching wherein said monitor region serves as an isolation groove to isolate said semiconductor laser element and

wherein adjacent sidewalls of said pair of second supports extend directly downward into an underlying substrate forming an isolation groove between said adjacent sidewalls, and a ratio of an area of said first and second supports relative to [[an]]a chip area of said semiconductor laser element is set within a range from more than 33% to less than 52%.

2. (Previously Presented) The semiconductor laser element according to Claim 1, wherein each support of the pair of second supports is provided corresponding to each ridge.

3.-11. (Cancelled)

12. (Previously Presented) The semiconductor laser element according to Claim 1, wherein the ratio of the area of said first and second supports relative to the area of said semiconductor laser element is set within a range from more than 44% to less than 50%.

13. (Previously Presented) A method for manufacturing the semiconductor laser element according to Claim 1 or 2, comprising:

arranging a plurality of ridges in parallel with each other on an element surface and providing each ridge with a plurality of supports to sandwich each ridge;

providing a block layer on surfaces of said ridges and said supports;

applying a protective film by spin coating to a surface of said block layer;

removing said protective film covering a top surface of said ridges;

removing said block layer covering the top surface of said ridges with said protective film serving as a mask; and

providing an electrode layer covering said ridges.